

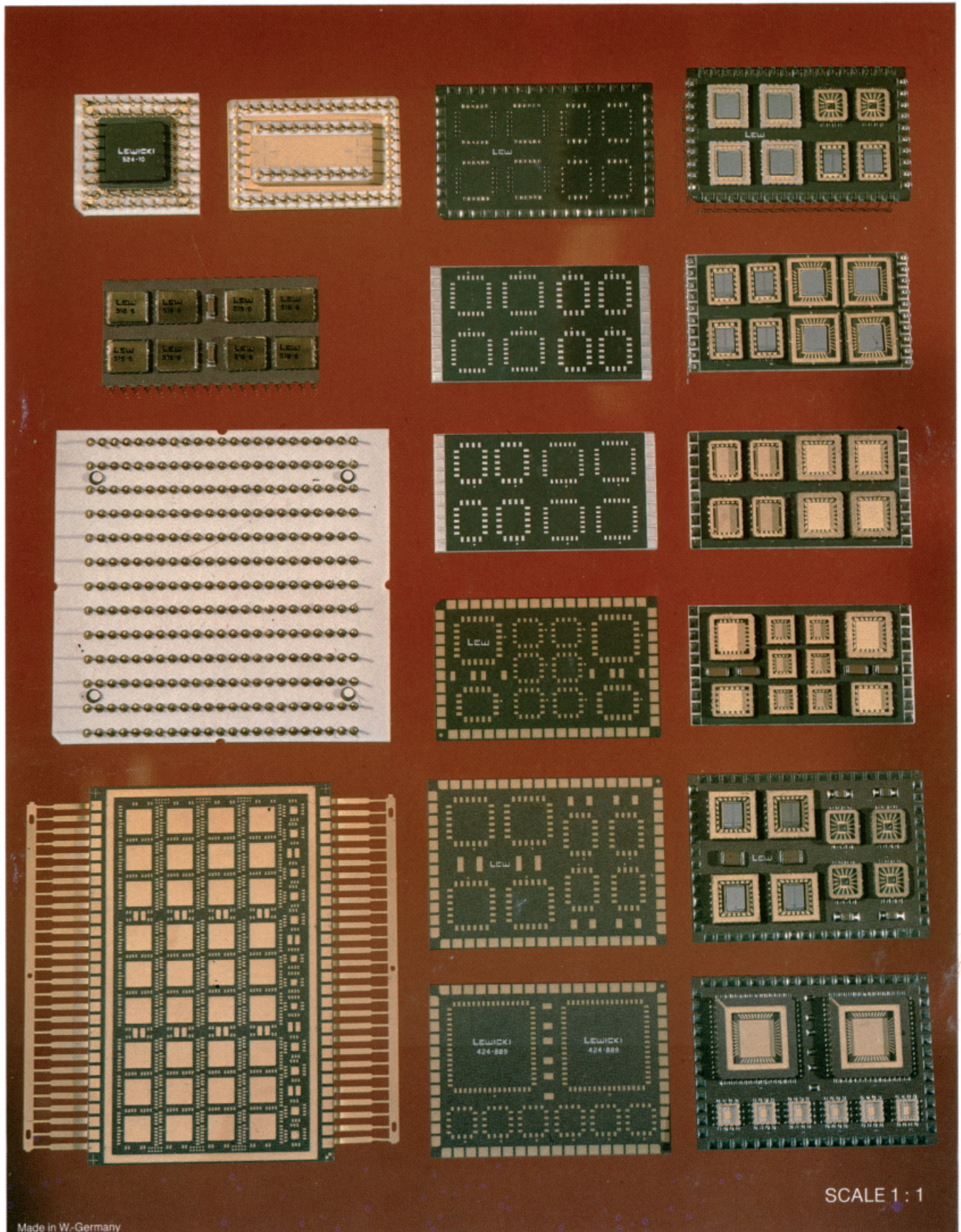
Kunden / custom

LEWICKI 20 Jahre Hybrid-ICs Pioniers

HYBRID-ICs
LEWICKI
Micro-electronic®
SPACE-PACKs

Chip Carrier Arrays

hi-rel, compact ceramic multilayer motherboards



- ★ hermetically buried conductors
- ★ low ohmic conductor paths
- ★ fine line, high density
3-dimensional interconnections

- ★ black and white ceramic
- ★ beryllia for high heat dissipation
- ★ for Chip Carrier reflow soldering
(or direct chip attach under lids)

- ★ single and double sided capability
- ★ optoelectronic multiple arrays
- ★ side leads or pin grid array
etc.

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